

Q2
4. (Amended) The interconnection element of claim 1, wherein the transformable property is such that a first volume of one of the first element material and the second element material is adapted to be transformed to a different second volume.

Q3
9. (Amended) The interconnection element of claim 1, wherein at least one of the first element material and the second element material are introduced by plating.

Q4
13. (Amended) The interconnection element of claim 4, wherein the first element material is an alloy comprising palladium/cobalt and an activation layer comprises one of copper and nickel.

Q5
23. (Amended) The electronic component of claim 22, further comprising:
a plurality of conductive signal lines associated with the substrate; and
in the plurality of free-standing resilient interconnection elements coupled to the substrate,
the base of the interconnection element electrically contacts a corresponding one of the signal lines.

Q6
48. (Amended) An assembly comprising:
a first substrate having a plurality of first contact nodes formed on the first substrate and a plurality of free-standing resilient interconnection elements coupled to the first substrate in such a manner that a base of an interconnection element electrically contacts a corresponding one of the first contact nodes; and

a second substrate having a plurality of second contact nodes,
wherein the interconnection element comprises:

a first element material adapted to be coupled to the first substrate, and

a second element material coupled to the first element material, and one of the first element material and the second element material comprises a material having a transformable property such that upon transformation, a shape of the interconnection element is modified,

wherein the interconnection element has a portion thereof which is capable of moving to a first position in which the interconnection element is in contact with one of the plurality of second contact nodes.

Q7
76. (Amended) A system for contacting an electronic device including an assembly comprising:
a first substrate having a plurality of first contact nodes formed on the first substrate and a plurality of free-standing resilient interconnection elements coupled to the first substrate in such a manner that a base of an interconnection element electrically contacts a corresponding one of the first contact nodes; and

a second substrate having a plurality of second contact nodes,

wherein the interconnection element comprises:

a first element material adapted to be coupled to the first substrate, and

a second element material coupled to the first element material, and one of the first

027 B4 element material and the second element material comprises a material having a transformable property such that upon transformation, a shape of the interconnection element is modified,

wherein the interconnection element has a portion thereof which is capable of moving to a first position in which the interconnection element is in contact with one of the plurality of second contact nodes.
